

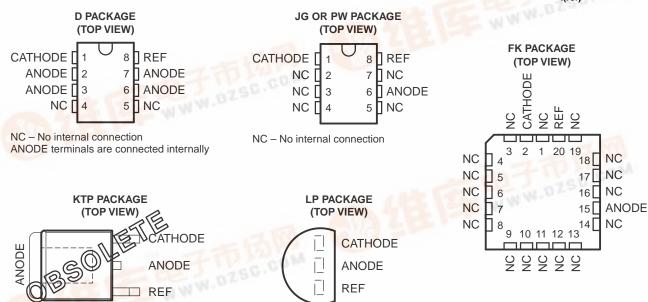
TL1431 PRECISION PROGRAMMABLE REFERENCE

SLVS062K-DECEMBER 1991-REVISED OCTOBER 2006

FEATURES

- 0.4% Initial Voltage Tolerance
- 0.2-Ω Typical Output Impedance
- Fast Turnon...500 ns

- Sink Current Capability...1 mA to 100 mA
- Low Reference Current (REF)
- Adjustable Output Voltage...V_{I(ref)} to 36 V



DESCRIPTION/ORDERING INFORMATION

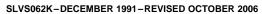
The TL1431 is a precision programmable reference with specified thermal stability over automotive, commercial, and military temperature ranges. The output voltage can be set to any value between $V_{I(ref)}$ (approximately 2.5 V) and 36 V with two external resistors (see Figure 16). This device has a typical output impedance of 0.2 Ω . Active output circuitry provides a very sharp turnon characteristic, making the device an excellent replacement for Zener diodes and other types of references in applications such as onboard regulation, adjustable power supplies, and switching power supplies.

The TL1431C is characterized for operation over the commercial temperature range of 0°C to 70°C. The TL1431Q is characterized for operation over the full automotive temperature range of –40°C to 125°C. The TL1431M is characterized for operation over the full military temperature range of –55°C to 125°C.

PDPlease be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas

instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TL1431 PRECISION PROGRAMMABLE REFERENCE





ORDERING INFORMATION(1)

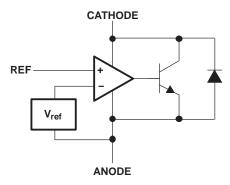
T _A	PACKAGE		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PowerFLEX™ – KTP	Reel of 3000	TL1431CKTPR	OBSOLETE	
	SOIC - D	Tube of 75	TL1431CD	- 1431C	
	30IC - D	Reel of 2500	TL1431CDR	14310	
0°C to 70°C	TO-226 / TO-92 – LP	Bulk of 1000	TL1431CLP	TI 4424C	
	10-226 / 10-92 – LP	Reel of 2000	TL1431CLPR	TL1431C	
	TSSOP – PW	Tube of 150	TL1431CPW	- T1431	
		Reel of 2000	TL1431CPWR	11431	
	SOIC - D	Tube of 75	TL1431QD	- TL1431QD	
-40°C to 125°C	30IC - D	Reel of 2500	TL1431QDR	TE143TQD	
-40°C to 125°C	TSSOP – PW	Tube of 150	TL1431QPW	T4 404 ODW	
	1330P – PW	Reel of 2000	TL1431QPWR	T1431QPW	
-55°C to 125°C	CDIP – JG	Tube of 50	TL1431MJG	TL1431MJG	
	LCCC – FK	Tube of 55	TL1431MFK	TL1431MFK	

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



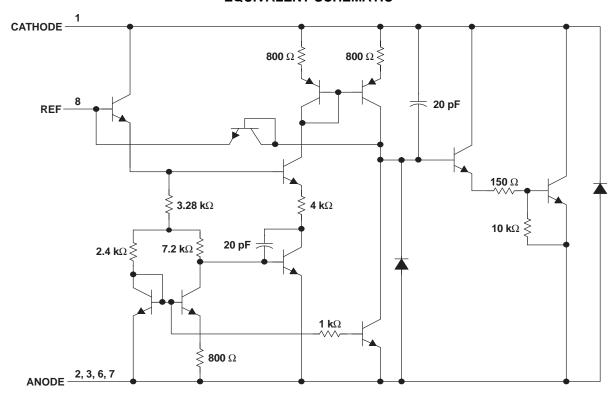


FUNCTIONAL BLOCK DIAGRAM





EQUIVALENT SCHEMATIC



- All component values are nominal.
- B. Pin numbers shown are for the D package.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{KA}	Cathode voltage (2)		37	V	
I _{KA}	Continuous cathode current range	-100	150	mA	
I _{I(ref)}	Reference input current range	-50	10	mA	
		D package		97	
θ_{JA}	Package thermal impedance (3)(4)	LP package		140	°C/W
		PW package		149	
0	Package thermal impedance (5)(6)	FK package		5.61	°C/W
θ_{JC}	Fackage thermal impedance (1707)	JG package		14.5	C/VV
T_J	Operating virtual junction temperature		150	Ô	
	Lead temperature	1,6 mm (1/16 in) from case for 10 s		260	°C
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ All voltage values are with respect to ANODE, unless otherwise noted.

Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

Maximum power dissipation is a function of $T_{J(max)}$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_{J(max)} - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

⁽⁶⁾ The package thermal impedance is calculated in accordance with MIL-STD-883.

TL1431 PRECISION PROGRAMMABLE REFERENCE





Recommended Operating Conditions

			MIN	MAX	UNIT
V _{KA}	Cathode voltage		V _{I(ref)}	36	V
I _{KA}	Cathode current		1	100	mA
		TL1431C	0	70	
T _A	Operating free-air temperature	TL1431Q	-40	125	°C
		TL1431M	-55	125	

Electrical Characteristics

at specified free-air temperature, $I_{KA} = 10 \text{ mA}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T (1)	T _A ⁽¹⁾ TEST		TL1431C			
	PARAMETER	TEST CONDITIONS	IA'''	'A' CIRCUIT		TYP	MAX	UNIT	
V	Deference input valtage	M M	25°C	Figure 4	2490	2500	2510	mV	
V _{I(ref)}	Reference input voltage	$V_{KA} = V_{I(ref)}$	Full range	Figure 1	2480		2520	IIIV	
V _{I(dev)}	Deviation of reference input voltage over full temperature range ⁽²⁾	$V_{KA} = V_{I(ref)}$	Full range	Figure 1		4	20	mV	
$\frac{\Delta V_{\text{l(ref)}}}{\Delta V_{\text{KA}}}$	Ratio of change in reference input voltage to the change in cathode voltage	$\Delta V_{KA} = 3 \text{ V to } 36 \text{ V}$	Full range	Figure 2		-1.1	-2	mV/V	
	Reference input current	R1 = 10 kΩ, R2 = ∞	25°C		1.5	2.5			
I _{I(ref)}	Reference input current	$K1 = 10 \text{ K}22, K2 = \infty$	Full range	Figure 2			3	μΑ	
I _{I(dev)}	Deviation of reference input current over full temperature range ⁽²⁾	R1 = 10 kΩ, R2 = ∞	Full range	Figure 2		0.2	1.2	μΑ	
I _{min}	Minimum cathode current for regulation	$V_{KA} = V_{I(ref)}$	25°C	Figure 1		0.45	1	mA	
Off state sethade surrent		V - 26 V V - 0	25°C	25°C 0.18	0.5	^			
I _{off}	Off-state cathode current	$V_{KA} = 36 \text{ V}, V_{I(ref)} = 0$	Full range	Figure 3			2	μΑ	
z _{KA}	Output impedance ⁽³⁾	$V_{KA} = V_{I(ref)}$, f \leq 1 kHz, $I_{KA} = 1$ mA to 100 mA	25°C	Figure 1		0.2	0.4	Ω	

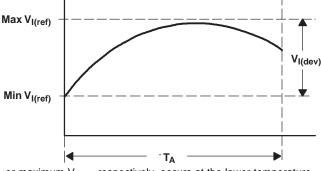
Full range is 0° C to 70° C for C-suffix devices.

The deviation parameters $V_{I(dev)}$ and $I_{I(dev)}$ are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage $\alpha_{VI(ref)}$ is defined as: $\frac{\left(\frac{V_{I(dev)}}{V_{I(ref)} \text{ at } 25^{\circ}\text{C}}\right) \times 10^{6}}{\text{Max } V_{I(ref)}}$ $\frac{\left(\frac{V_{I(dev)}}{V_{I(ref)} \text{ at } 25^{\circ}\text{C}}\right) \times 10^{6}}{\text{Max } V_{I(ref)}}$

$$\left| \alpha_{\text{vi(ref)}} \right| \left(\frac{\text{ppm}}{^{\circ}\text{C}} \right) = \frac{\left(\frac{^{\vee}\text{I(dev)}}{^{\vee}\text{I(ref)}} \text{ at 25°C} \right) \times 10^{6}}{T_{\text{A}}}$$

where:

 $\Delta T_{\mbox{\scriptsize A}}$ is the rated operating temperature range of the device.



 $\alpha_{VI(ref)}$ is positive or negative, depending on whether minimum $V_{I(ref)}$ or maximum $V_{I(ref)}$, respectively, occurs at the lower temperature.

(3) The output impedance is defined as: $|z_{\text{\tiny KA}}| = \frac{\Delta V_{\text{\tiny KA}}}{\Delta I_{\text{\tiny KA}}}$

When the device is operating with two external resistors (see Figure 2), the total dynamic impedance of the circuit is given by: $|z'| = \frac{\Delta V}{\Delta I}$, which is approximately equal to $\left| z_{_{KA}} \right| \left(1 + \frac{R1}{R2} \right)$

Electrical Characteristics

at specified free-air temperature, $I_{KA} = 10$ mA (unless otherwise noted)

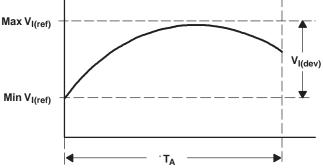
	PARAMETER	TEST CONDITIONS	T _A ⁽¹⁾	TEST TL1431Q TL1431M		M .	UNIT				
	PARAIVIETER	TEST CONDITIONS	IA''	CIRCUIT	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
			25°C		2490	2500	2510	2475	2500	2540	
V _{I(ref)}	Reference input voltage	$V_{KA} = V_{I(ref)}$	Full range	Figure 1	2470		2530	2460		2550	mV
V _{I(dev)}	Deviation of reference input voltage over full temperature range (2)	$V_{KA} = V_{I(ref)}$	Full range	Figure 1		17	55		17	55 ⁽³⁾	mV
$\frac{\Delta V_{\text{l(ref)}}}{\Delta V_{\text{KA}}}$	Ratio of change in reference input voltage to the change in cathode voltage	ΔV _{KA} = 3 V to 36 V	Full range	Figure 2		-1.1	-2		-1.1	-2	mV/V
			25°C			1.5	2.5		1.5	2.5	
I _{I(ref)}	Reference input current	R1 = 10 k Ω , R2 = ∞	Full range	Figure 2			4			5	μΑ
I _{I(dev)}	Deviation of reference input current over full temperature range (2)	R1 = 10 kΩ, R2 = ∞	Full range	Figure 2		0.5	2		0.5	3(3)	μΑ
I _{min}	Minimum cathode current for regulation	V _{KA} = V _{I(ref)}	25°C	Figure 1		0.45	1		0.45	1	mA
	Off-state cathode		25°C			0.18	0.5		0.18	0.5	
I _{off}	current	$V_{KA} = 36 \text{ V}, V_{I(ref)} = 0$	Full range	Figure 3			2			2	μΑ
z _{KA}	Output impedance ⁽⁴⁾	$V_{KA} = V_{I(ref)}$, $f \le 1 \text{ kHz}$, $I_{KA} = 1 \text{ mA to } 100 \text{ mA}$	25°C	Figure 1		0.2	0.4		0.2	0.4	Ω

Full range is -40° C to 125° C for Q-suffix devices and -55° C to 125° C for M-suffix devices.

The deviation parameters $V_{I(dev)}$ and $I_{I(dev)}$ are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage $\alpha_{VI(ref)}$ is defined as:

where:

 ΔT_A is the rated operating temperature range of the device.



 $\alpha_{VI(ref)}$ is positive or negative, depending on whether minimum $V_{I(ref)}$ or maximum $V_{I(ref)}$, respectively, occurs at the lower temperature. On products compliant to MIL-PRF-38535, this parameter is not production tested. The output impedance is defined as: $|Z_{KA}| = \frac{\Delta V_{KA}}{\Delta I_{KA}}$

When the device is operating with two external resistors (see Figure 2), the total dynamic impedance of the circuit is given by: $|Z'| = \frac{\Delta V}{\Delta I}$, which is approximately equal to $\left|z_{\text{KA}}\right|\left(1+\frac{R1}{R2}\right)$



PARAMETER MEASUREMENT INFORMATION

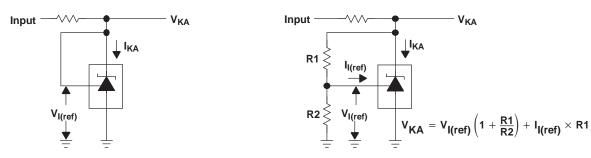


Figure 1. Test Circuit for $V_{(KA)} = V_{ref}$

Figure 2. Test Circuit for $V_{(KA)} > V_{ref}$

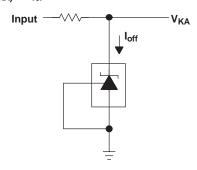


Figure 3. Test Circuit for $I_{\rm off}$

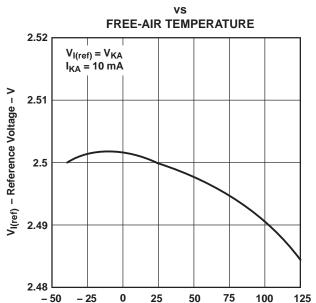
TYPICAL CHARACTERISTICS

Data at high and low temperatures are applicable only within the recommended operating free-air temperature ranges of the various devices.

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REFERENCE VOLTAGE



T_A – Free-Air Temperature – °C Figure 4.

CATHODE CURRENT

vs **CATHODE VOLTAGE** 150 $V_{KA} = V_{I(ref)}$ $T_A = 25^{\circ}C$ 100 I_{KA} - Cathode Current - mA 50 0 - 50 - 100 - 150 - 3 - 2 0 2 3 V_{KA} - Cathode Voltage - V

Figure 6.

REFERENCE CURRENT

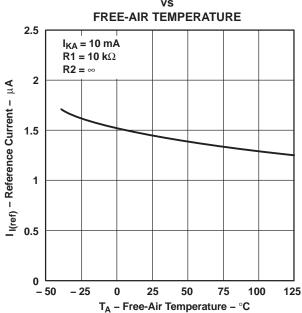


Figure 5.

CATHODE CURRENT vs

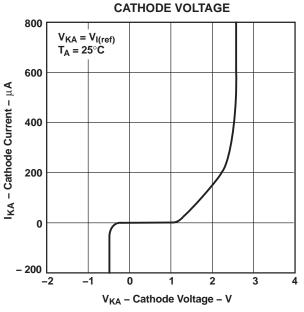


Figure 7.





FREE-AIR TEMPERATURE 0.4 $V_{KA} = 36 V$ I KA(off) - Off-State Cathode Current - µA $V_{I(ref)} = 0$ 0.35 0.3 0.25 0.2 0.15 0.1 0.05 - 25 25 75 100 125 -50

RATIO OF DELTA REFERENCE VOLTAGE TO DELTA CATHODE VOLTAGE

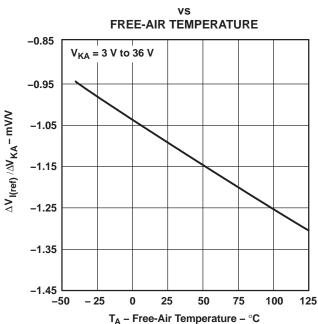
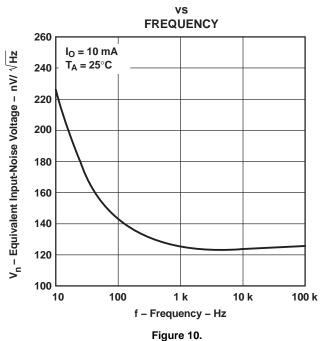


Figure 8.

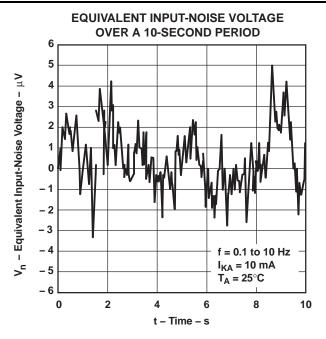
 T_A – Free-Air Temperature – $^{\circ}C$

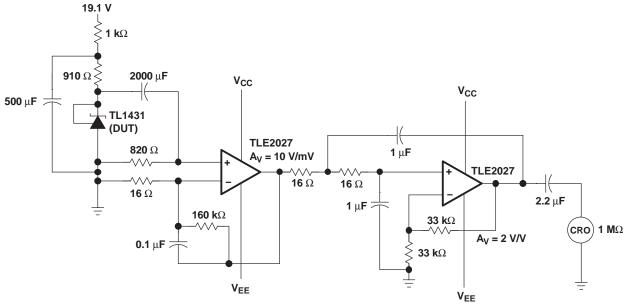
Figure 9.

EQUIVALENT INPUT-NOISE VOLTAGE





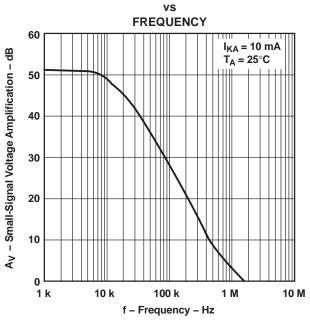


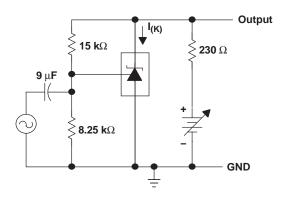


TEST CIRCUIT FOR 0.1-Hz TO 10-Hz EQUIVALENT INPUT-NOISE VOLTAGE Figure 11.



SMALL-SIGNAL VOLTAGE AMPLIFICATION



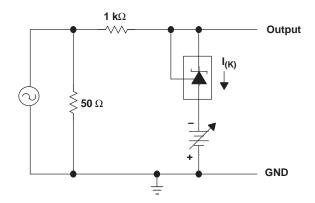


TEST CIRCUIT FOR VOLTAGE AMPLIFICATION

Figure 12.

REFERENCE IMPEDANCE

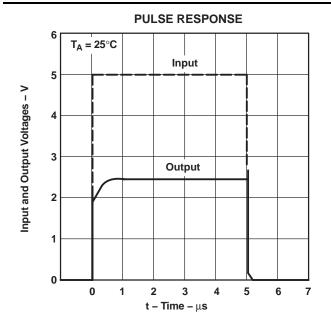
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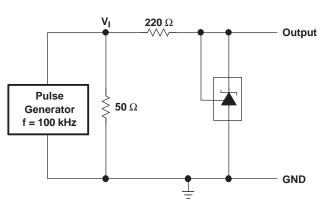


TEST CIRCUIT FOR REFERENCE IMPEDANCE

Figure 13.

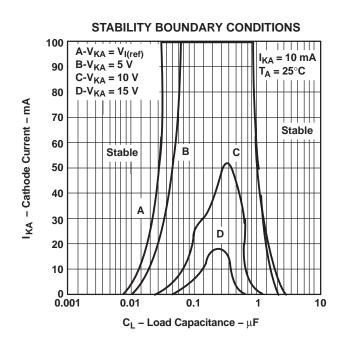
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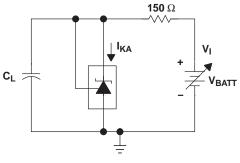




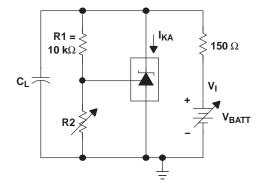
TEST CIRCUIT FOR PULSE RESPONSE

Figure 14.





TEST CIRCUIT FOR CURVE A



TEST CIRCUIT FOR CURVES B, C, AND D

A. The areas under the curves represent conditions that may cause the device to oscillate. For curves B, C, and D, R2 and V+ are adjusted to establish the initial V_{KA} and I_{KA} conditions, with $C_L = 0$. V_{BATT} and C_L then are adjusted to determine the ranges of stability.

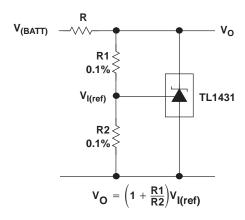
Figure 15.



APPLICATION INFORMATION

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A. R should provide cathode current ≥1 mA to the TL1431 at minimum $V_{(BATT)}$. Figure 16. Shunt Regulator

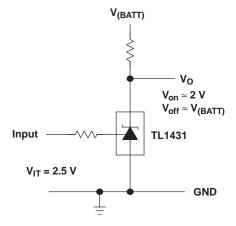
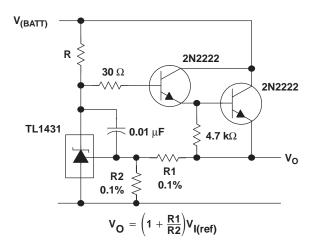


Figure 17. Single-Supply Comparator With Temperature-Compensated Threshold

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A. R should provide cathode current ≥1 mA to the TL1431 at minimum V_(BATT).
 Figure 18. Precision High-Current Series Regulator

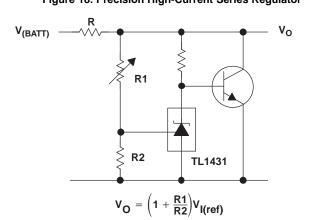


Figure 20. Higher-Current Shunt Regulator

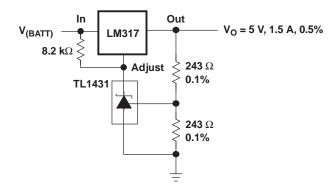


Figure 22. Precision 5-V, 1.5-A, 0.5% Regulator

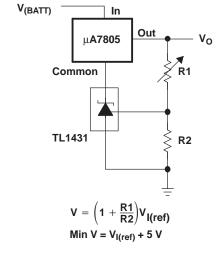
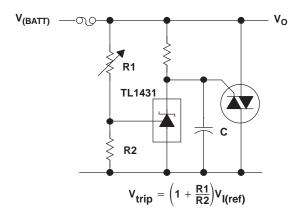
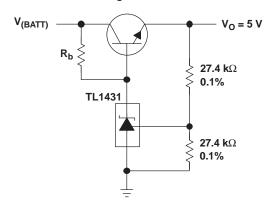


Figure 19. Output Control of a Three-Terminal Fixed Regulator



 Refer to the stability boundary conditions in Figure 15 to determine allowable values for C.

Figure 21. Crowbar



A. R_b should provide cathode current ≥ 1 mA to the TL1431.

Figure 23. 5-V Precision Regulator



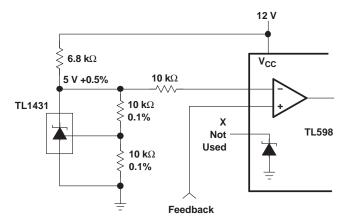
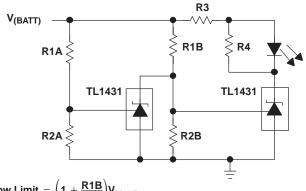


Figure 24. PWM Converter With 0.5% Reference



 $\begin{aligned} &\text{Low Limit} = \left(1 + \frac{R1B}{R2B}\right) V_{\text{I(ref)}} & &\text{LED on When} \\ &\text{High Limit} = \left(1 + \frac{R1A}{R2A}\right) V_{\text{I(ref)}} & &\text{Low Limit} < V_{\text{(BATT)}} < \text{High Limit} \end{aligned}$

A. Select R3 and R4 to provide the desired LED intensity and cathode current ≥1 mA to the TL1431.

Figure 25. Voltage Monitor

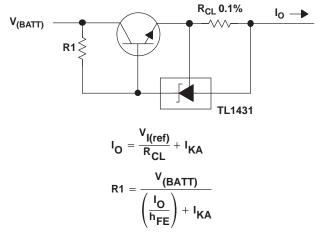
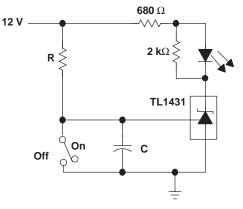


Figure 27. Precision Current Limiter



Delay =
$$R \times C \times I_{1} \frac{12 \text{ V}}{(12 \text{ V}) - V_{1(\text{ref})}}$$

Figure 26. Delay Timer

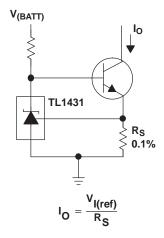


Figure 28. Precision Constant-Current Sink





6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9962001Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9962001QPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9962001VPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TL1431CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1431CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1431CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1431CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1431CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1431CKTPR	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
TL1431CLP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
TL1431CLPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
TL1431CLPM	OBSOLETE	TO-92	LP	3		TBD	Call TI	Call TI
TL1431CLPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
TL1431CLPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
TL1431CPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1431CPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1431CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1431CPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1431MFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL1431MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL1431MJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TL1431MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TL1431QD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
TL1431QDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
TL1431QLP	OBSOLETE	TO-92	LP	3		TBD	Call TI	Call TI
TL1431QLPR	OBSOLETE	TO-92	LP	3		TBD	Call TI	Call TI
TL1431QPWR	ACTIVE	TSSOP	PW	8	2000	TBD	CU NIPDAU	Level-1-250C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



PACKAGE OPTION ADDENDUM

6-Dec-2006

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

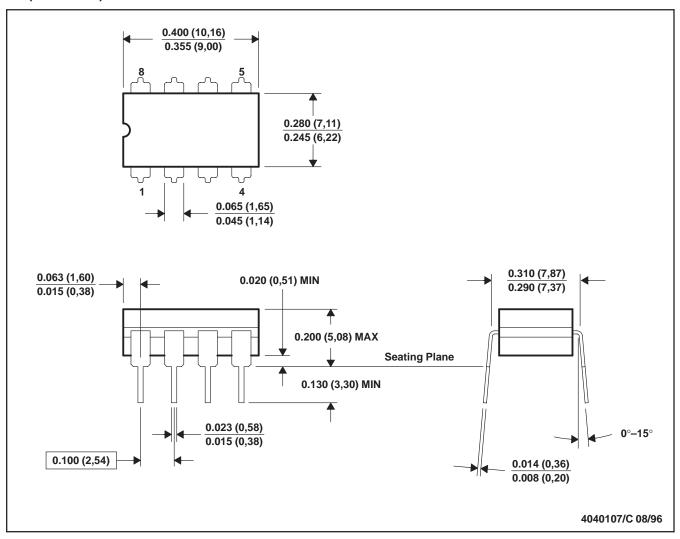
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

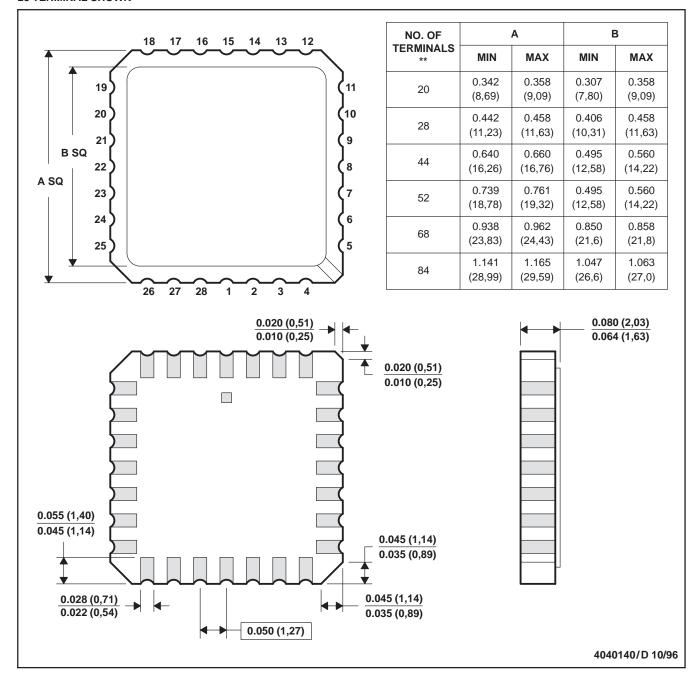
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER

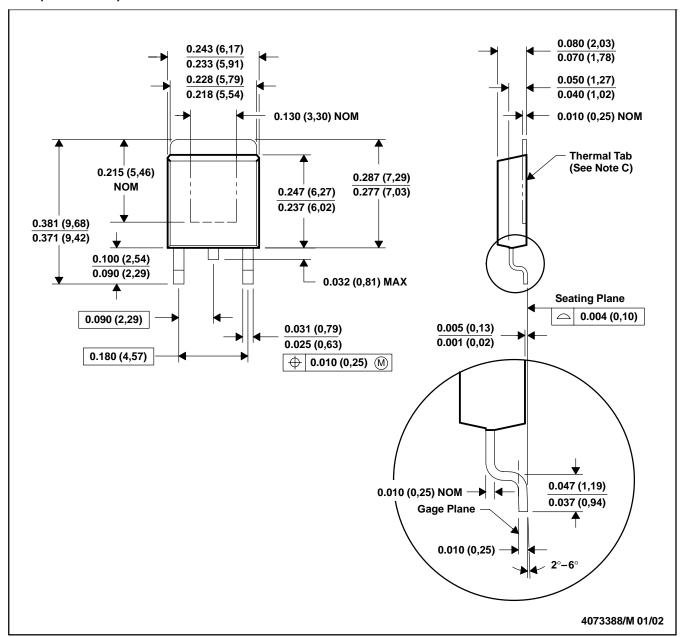


- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



KTP (R-PSFM-G2)

PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

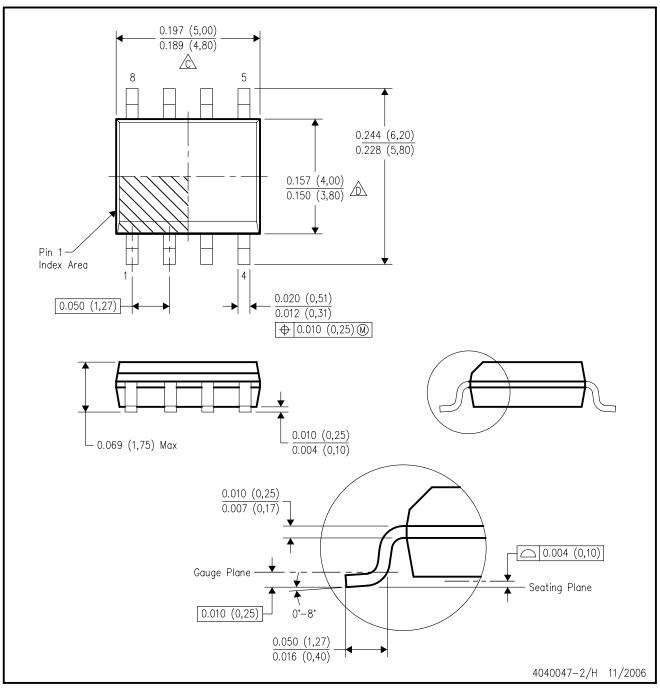
- B. This drawing is subject to change without notice.
- C. The center lead is in electrical contact with the thermal tab.
- D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
- E. Falls within JEDEC TO-252 variation AC.

PowerFLEX is a trademark of Texas Instruments.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



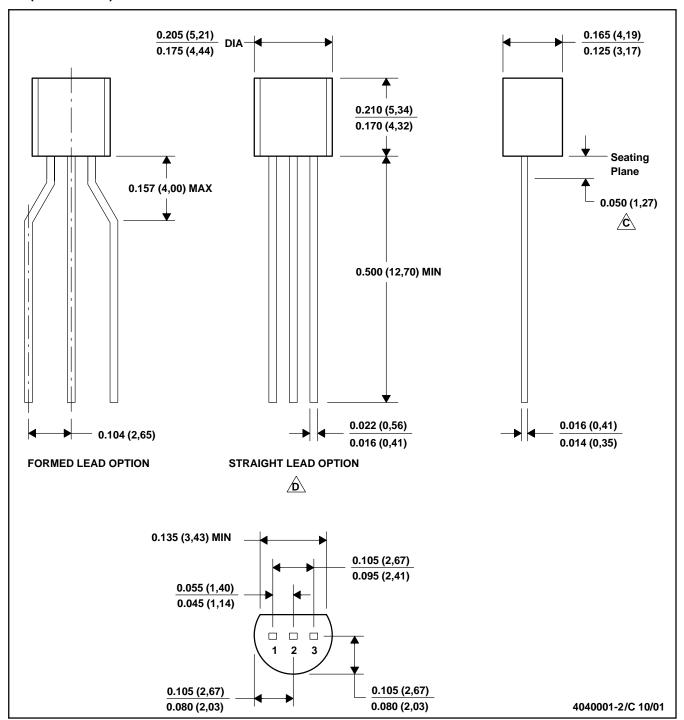
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C.\ Lead dimensions are not controlled within this area

D.\ FAlls within JEDEC TO -226 Variation AA (TO-226 replaces TO-92)

E. Shipping Method:

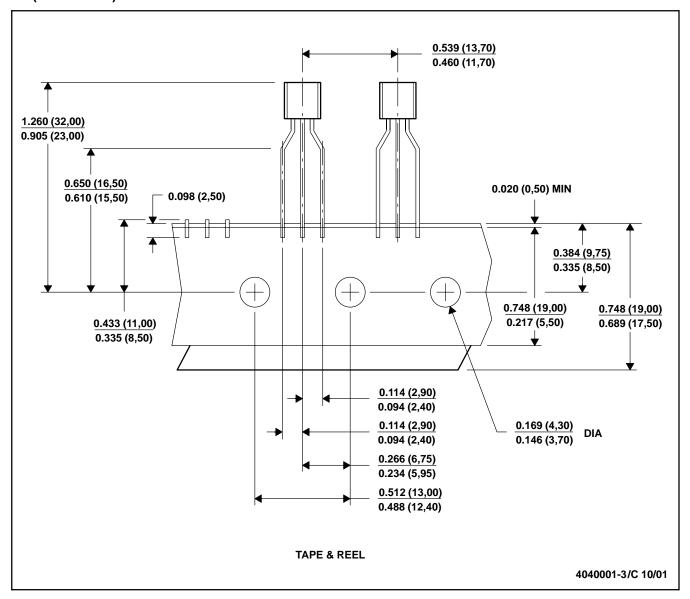
Straight lead option available in bulk pack only.

Formed lead option available in tape & reel or ammo pack.



LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Tape and Reel information for the Format Lead Option package.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153

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